

IN THE SPECIFICATION

Please replace paragraph [0020] with the following new paragraph:

[0020] As illustrated, for the embodiment, TEC **110** is disposed in the lower portion of substrate **112**, and the "step" or higher portion of substrate **112** has a height that is substantially the same as TEC **110**, to allow laser light source **102** to be substantially co-planar with the "top" surface of the step or higher portion of substrate **112**. As illustrated, this feature allows e.g. a driver or an amplifier **104** to be optionally placed in very close proximity of laser light source **102**. For these embodiments, vias **122b** are employed to facilitate routing of electrical connections from selected one(s) of I/O pins **116** to optional driver/amplifier **104**. The co-planar and proximal attributes enable relatively short leads **105** to be employed to electrically couple laser light source **102** to optional driver or amplifier **104** (if it is disposed as shown). The arrangement potentially contributes to improving the performance of optoelectronic modules **100**.